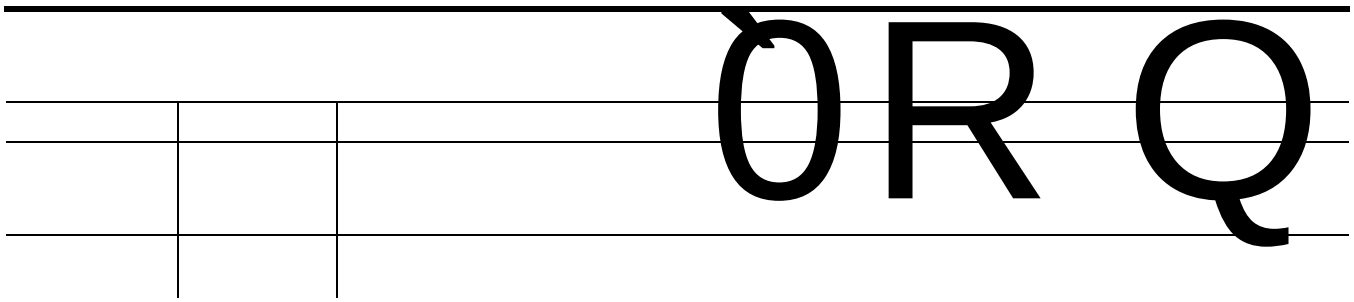
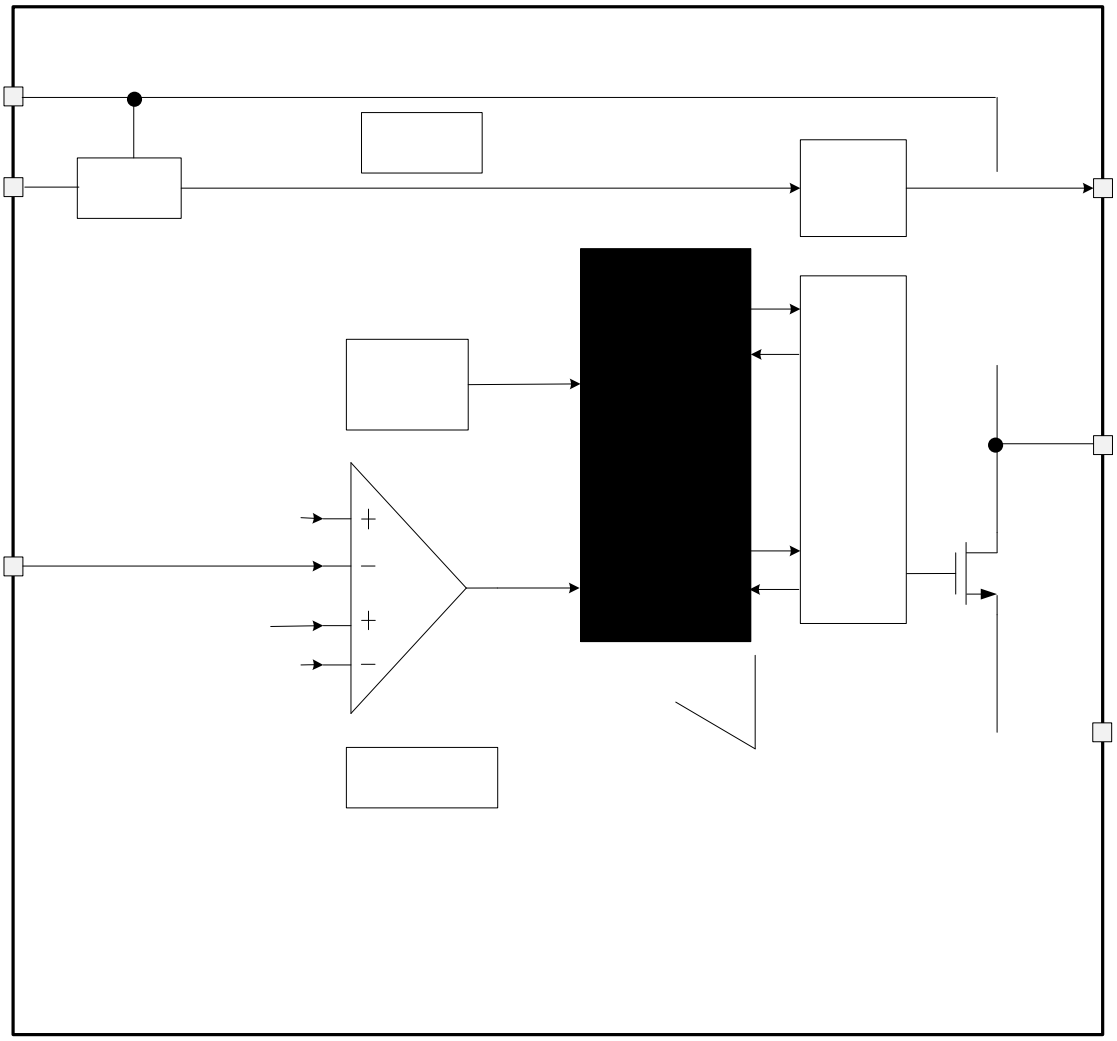
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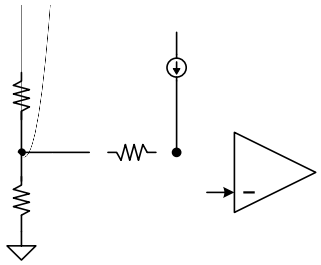


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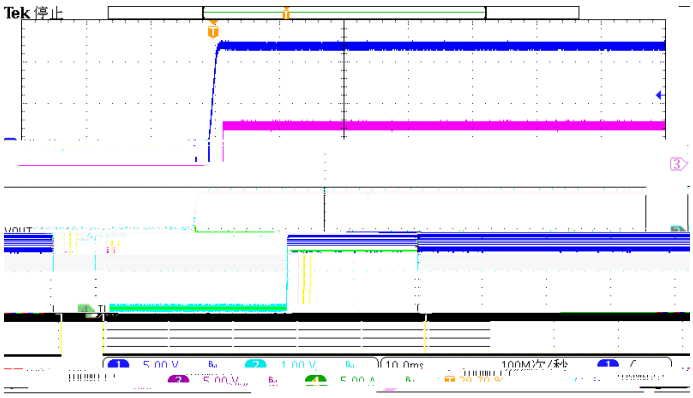


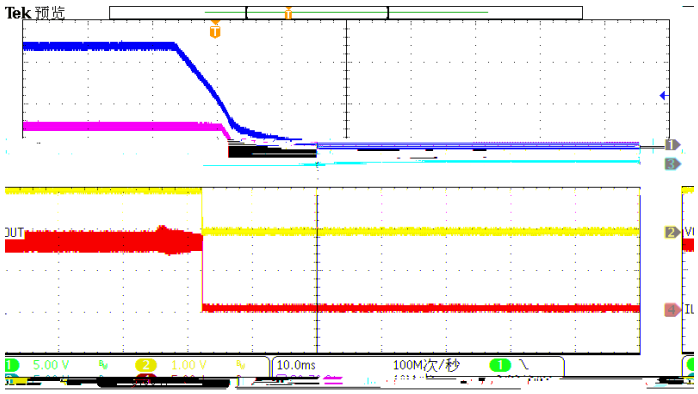


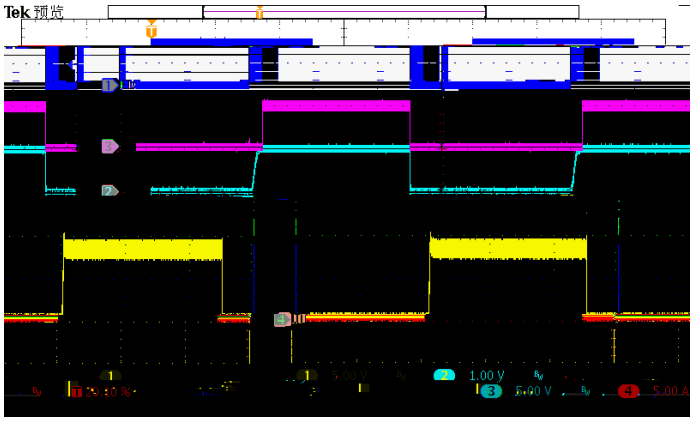
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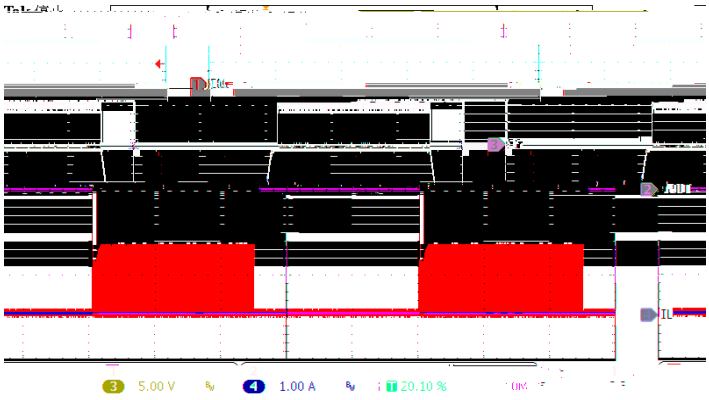
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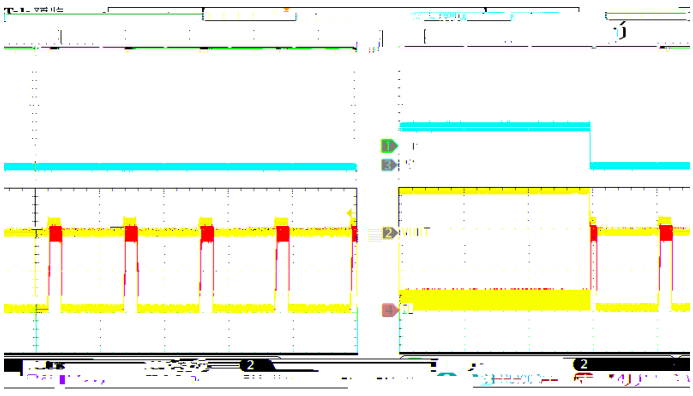
YROWDJH

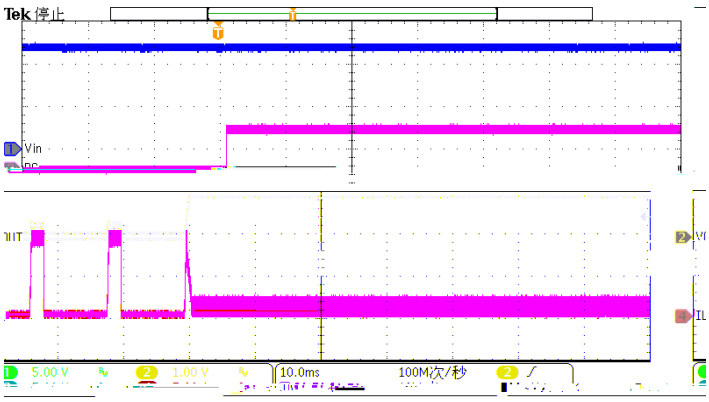

Tek 停止
5.00 V
1.00 V
10.0ms
100M次/秒


Tek 预览
5.00 V
1.00 V
10.0ms
100M次/秒

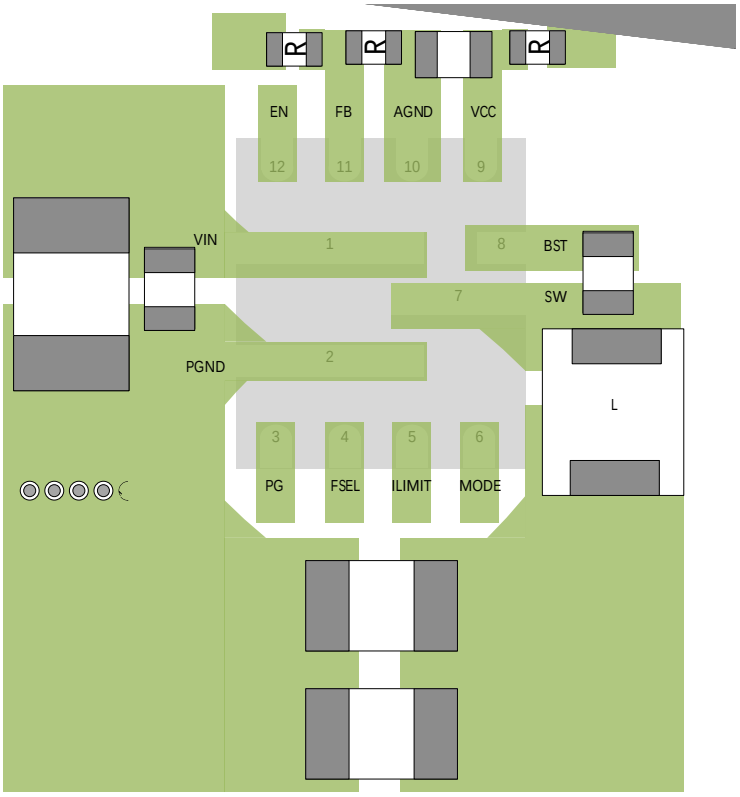

Tek 预览
1.00 V

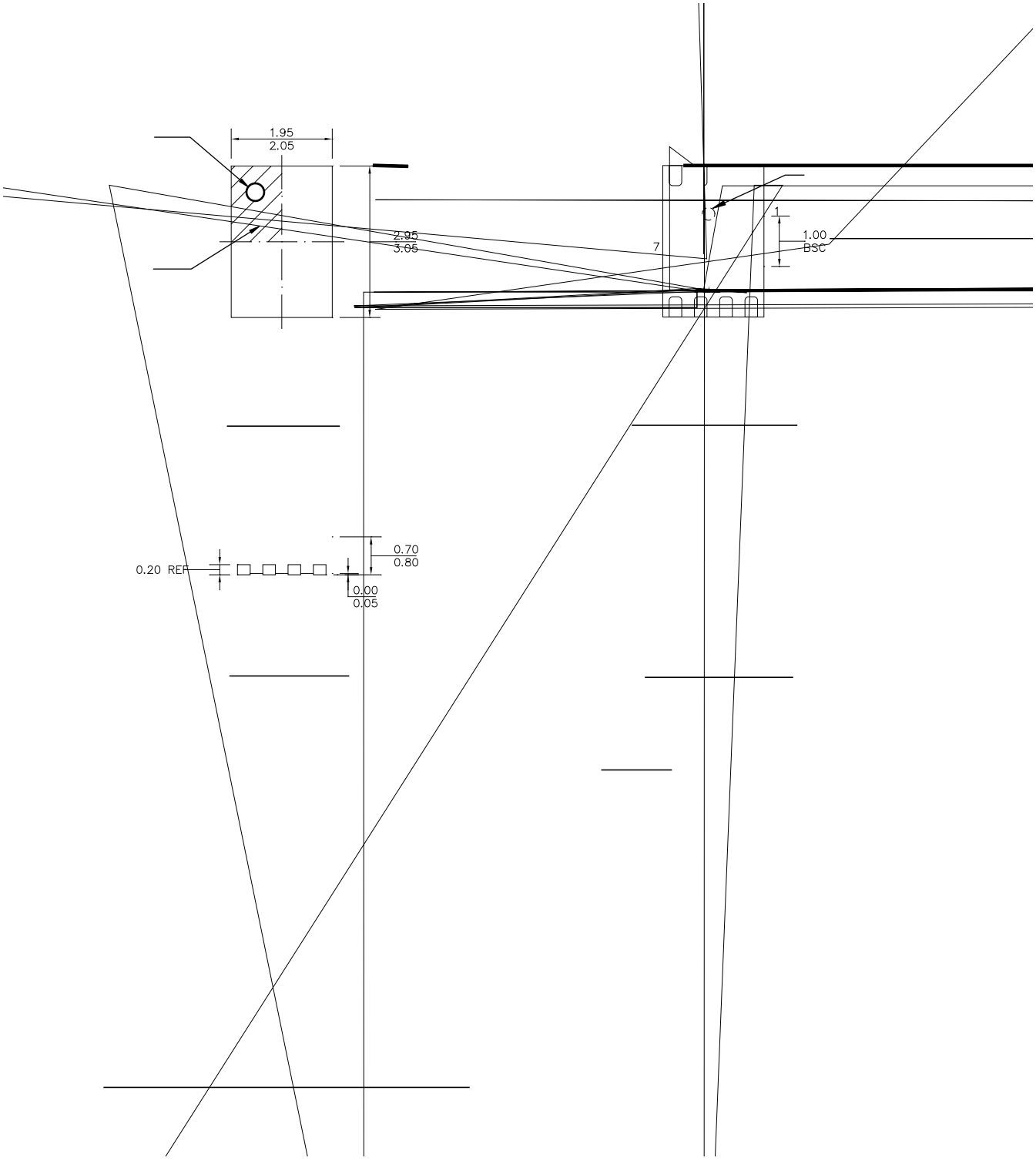

5.00 V
1.00 A
20.10 %




Tek 停止
Vin
5.00 V
1.00 V
10.0ms
100M次/秒

The bottom layer is a large ground plane connected to the ground plane on top layer by vias It is recommended to use 8mil diameter drill holes of thermal vias, but a smaller via offers less risk of solder volume loss. On applications where solder volume loss thru the vias is of concern, plugging or tenting can be used to achieve a repeatable process.




1.95
2.05
2.95
3.05
1.00
BSC
0.70
0.80
0.20 REF
0.00
0.05

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